## **Amendments to the Specification:**

Please add the following <u>new</u> paragraph after the title and before the paragraph on page 1: THIS APPLICATION IS A U.S. NATIONAL PHASE APPLICATION OF PCT INTERNATIONAL APPLICATION PCT/JP2004/009265.

Please replace paragraph [0024] with the following amended paragraph:

## [0024]

- FIG. 1 shows a typical construction of an LED array, a distributed index rod lens array, and a photosensitive drum used in a conventional optical printer.
  - FIG. 2 shows a shape of a light-emitting area.
- FIG. 3 shows a light ray to a photosensitive drum in the case that a conventional lens-attached LED array is used.
- FIG. 4 shows FIGS. 4A and 4B show an embodiment of the lens-attached lightemitting element in accordance with the present invention.
- FIG. 5 shows a light ray to a photosensitive drum in the case that a lens-attached LED array in accordance with the present invention.
- FIG. 6 showsFIGS. 6A and 6B show the distribution of amount of light of pixel image formed on the photosensitive drum through the rod lens array by utilizing the composite lens array.
- FIG. 7 shows another embodiment of the lens-attached light emitting element in accordance with the present invention.
- FIG. 8 shows a cross-sectional view of an embodiment of a lens-attached lightemitting element provided with an antireflection film.
- FIG. 9 shows an equivalent circuit of the self-scanning light-emitting element array.
  - FIG.10 shows a chip of the self-scanning light-emitting element array.
- FIG. 11 is an enlarged view of a part of the light-emitting thyristors provided with a composite lens array.
- FIG. 12 shows a side view of the light-emitting thyristor provided with the composite lens array in FIG. 11.
- FIG. 13 shows a process for manufacturing a lens-attached light-emitting thyristor array of the self-scanning light-emitting element array.
- FIG. 14 shows a plan view of the silica glass substrate provided with the Cr film in which an array of openings is patterned.

FIG. 15 shows a condition where a wafer is cut.

FIG. 16 shows a process for manufacturing a lens-attached light-emitting thyristor array of the self-scanning light-emitting element array.

IG.FIG. 17 shows a light-emitting thyristor array chip on which an adhesive tape is adhered.

FIG. 18 shows a plan view of a silica glass substrate provided with the Cr film in which an opening array is patterned.